



# Product Change Notification

## 107598 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 107598 - 00  
**Change Title:** Intel Carrier Grade Server TIGW1U, PCN 107598-00, Product Design, Changes to AC Power Distribution Board, Fan Bracket Assembly, DVDCDR, Software Update, SAS OpROM, update PCI-X riser, update Deployment CD, add Battery Isolation.  
**Date of Publication:** Aug 01, 2007

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Aug 31, 2007
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## Description of Change to the Customer:

### Top Assembly change from D74314-006 to D74314-007

1. Update PDB in Power Supply.

### Top Assembly change from D74314-007 to D74314-008

2. Change from soft tooled CPU fan bracket to hard tooled CPU fan bracket to reduce hard drive rotational vibration.

### Top Assembly Change from D74314-008 to D74314-009

- 3a. Change DVDCDR part from Lite-On SSC-2485K to Sony CRX880A due to end of life of Lite-On part.
- 3b. Change Software Update Package to BIOS79, HB\_BMC16, FHB12.
  - Fix to HW RAID SSID
  - Fix to enable external SAS x4 port on rear of chassis
  - Fix to allow for G Stepping of 64-bit Dual-Core Intel Xeon 5100 series processors.
  - Please refer to release notes available online for SUP17 for additional changes included in this update.

3c. Change LSI-OpROM code from Phase7 to Phase9.

- Fix the SW RAID SSID
- Fix OpROM/Driver related issues with Windows Drivers.

3d. Change gold plating thickness on PCI-X Riser board connector from 15u" (D73983-002) to board with 30u" (C81343-151) of Gold to improve long term reliability.

3e. Update Deployment CD

- Deployment CD with updated drivers and documentation

3f. Add battery isolator.

Add battery isolator around battery. As seen in Figure 1, the PCI assembly mechanical assembly is very close to the battery. In order to reduce the chance of the PCI riser card assembly from touching the battery during removal and insertion, a battery isolator is being installed around the battery. Figure 2 shows the battery isolation in place.

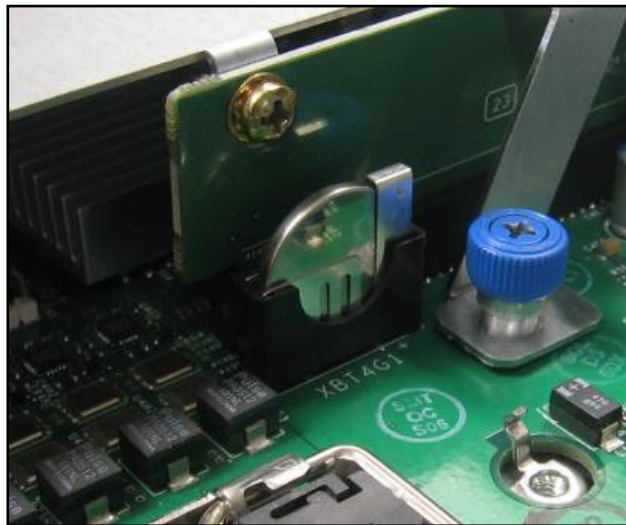


Figure 1. Battery in Relation to PCI Assembly Leg



Figure 2. Battery Isolation in Place

## Customer Impact of Change and Recommended Action:

1. No customer impact.
2. No customer impact.
- 3a. No customer impact anticipated, customer may wish to test.
- 3b. Customers should perform validation. The SUP17 release notes and latest associated drivers can be found here: <http://www.intel.com/design/servers/cg/tigw1u/tools.htm>
- 3c. Customers should perform validation using related Phase 9 drivers, available at: <http://www.intel.com/design/servers/cg/tigw1u/tools.htm>
- 3d. PCI-X riser board C81343-151 is improved process, and may be retrofitted into pre-(put the TA# here) systems with spare part TMWPCIXRSR01W.
- 3e. No customer impact.
- 3f. No customer impact.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
TMWA0201W	885431	D74314-006	D74314-007
TMWA0201W	885431	D74314-007	D74314-008
TMWA0201W	885431	D74314-008	D74314-009

## Reference Documents / Attachments:

**Document:** \_\_\_\_\_ **Location #:** \_\_\_\_\_

## PCN Revision History:

Date of Revision:	Revision Number:	Reason:
Aug 01, 2007	00	Originally Published PCN